

ABSTRACT OF THE DISCLOSURE

A polishing pad for polishing semiconductors and
5 other planar substrates in the presence of a slurry
comprising abrasive particles and a dispersive agent is
disclosed. The polishing pad includes a soluble component
within a polymer matrix component. The soluble component
includes particles soluble in the slurry sufficiently to
10 provide a void structure in the polishing surface of the
pad. The void structure enhances the polishing rate and
uniformity by increasing the mobility of the abrasive
particles while reducing scratching of the polished
surface. Additives that further enhance polishing and/or
15 assist in the removal of residues generated during
polishing, such as surfactants and removers, are
optionally incorporated in the soluble particles or
topographically coated on the soluble particles.

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